


Multi purpose wood fibre insulation board with very high compression strength

- Insulation board and height levelling board under screed systems
- Render carrying board for Clay and Lime plasters in internal construction
- High compression strength ≥ 150 kPa
- Contributes to the regulation of indoor air moisture
- Diffusion open for increased structural safety
- Wood from responsible forestry - PEFC certified

Application area


- Wood fibre board for floor constructions under wet and dry screed systems
- Pressure-resistant plaster base board on full-surface wooden substrates (≥ 15 mm) indoors
- Can be used as a single layer up to 40 mm under click parquet and click laminate ≥ 10 mm

Technical data

Produced and supervised according to	EN 13171
Board designation	WF – EN 13171 – T5 – CS (10\Y)150 – TR10 – MU5
Fire class (RTF) according to EN 13501-1	E
Permanent temperature range [°C]	≤ 100
Declared thermal conductivity [W/(m*K)]	0.048
Density [kg/m ³] (approx.)	250
Water vapour diffusion resistance factor μ	5
Specific heat capacity [J/(kg*K)]	2,100
Compressive strength at 10% compression δ_{10} [N/mm ²]	≥ 0.15
Compression strength [kPa]	≥ 150
Tensile strength perpendicular to face [kPa] (approx.)	≥ 10
Manufacturing process	wet process / utilisation of the wood's own lignin for panel bonding
Ingredients	Wood fibre, bond between layers
Declared level of airflow resistance [(kPa*s)/m ²]	≥ 100
Bonded carbon [kg CO ₂ equivalent./m ³] (approx.)	400

Additional technical data

Thickness [mm]	Declared thermal resistance $[(m^2 \cdot K)/W]$	s_d value [m]
20	0.40	0.10
40	0.80	0.20
60	1.25	0.30
80	1.65	0.40
100	2.05	0.50

Forms of delivery

Handy formats for flat surfaces

Thickness [mm]	Edge profile	Length [mm]	Width [mm]	Number/pal. [pcs.]	Coverage/pal. gross [m ²]
20	SE	1350	600	112	90.720
20	SE	2700	1200	56	181.440
40	SE	1350	600	56	45.360
60	SE	1350	600	38	30.780
80	SE	1350	600	28	22.680
100	SE	1350	600	22	17.820

Weight and packing

Handy formats for flat surfaces

Thickness [mm]	Edge profile	Length [mm]	Width [mm]	Weight/m ² [kg]	Weight/pcs. [kg]	pac./pal. paper/cardboard (approx) [kg]	pac./pal. plastic (approx) [kg]	pac./pal. wood (approx) [kg]	Weight./pal. (approx.) [kg]
20	SE	1350	600	5.20	4.2	0.10	1.0	20.3	495
20	SE	2700	1200	5.20	16.9	0.10	1.5	23.8	970
40	SE	1350	600	10.40	8.4	0.10	1.0	20.3	495
60	SE	1350	600	15.60	12.6	0.10	1.0	20.3	505
80	SE	1350	600	20.80	16.8	0.10	1.0	20.3	495
100	SE	1350	600	26.00	21.1	0.10	1.0	20.3	490

Notes

Storage

- Store wood fibre boards horizontally, flat and dry
- Protect edges from damage
- Only remove the film packaging when the ambient climate is dry and keep the pallet packing label
- Maximum stacking height: 4 pallets

Disposal

Waste cuttings:

- Waste code according to 2014/955/EU: 03 01 05

Dismantling:

- Waste code according to 2014/955/EU: 17 02 01

Cutting

- The boards can be cut to size using the band saw, circular saw, jigsaw and other wood-cutting tools.

Occupational health and safety

- Comply with local regulations for the processing of wood-fibre material
- Suitable protective measures must be taken when cutting the wood fibre insulation boards. (dust extraction, dust mask)

Building moisture

- Building moisture caused by e.g. fresh screed, plaster or paint must generally be removed by ventilation.
- Dry air must be ensured inside the building during the construction phase.
- Wood fibre insulation boards are delivered dry. On building sites the final material moisture is attained via acclimatisation
- Before plastering ensure the moisture content of the Wood-fibre insulation boards is 13%.

Installation

Installation in floor systems

- When laying on mineral substrates, a separating layer is recommended. This protects the wood fibreboard from rising residual moisture.
- Installation on full-surface substrate
- The product must be laid in a bond. (min. offset 250 mm)
- We recommend STEICO*soundstrip* as edge insulation strips for rising building components.
- When used in combination with wet screed, a separating layer must be planned.
- The local fire protection requirements must be observed in the area of the chimney and heating systems. (Observe clearances)

Installation for plastering

- The STEICO*base* can only be used for the interior.
- The STEICO*base* is fixed to a full-surface wooden substrate (min. 15mm thick) with screws or staples.
- The distance between the wide back staples in the width should be approx. 300 mm. The distance between the staples in height should be approx. 150 mm.
- Furthermore, when stapling the boards, butt joints should also be fixed with staples.
- The spacing for screw fixing should be approx. 250 mm in width and height.
- The wood fibre board can then be coated with the first layer of reinforcing plaster.
- The reinforcing mesh is then smoothed into the second layer of plaster.
- The surface can then be left as it is or a finishing render can be applied.
- We recommend a lime or clay plaster for the interior.

Certificates and quality management



 Caption**other abbreviations****pal.** Pallet**T&G** Tongue and Groove**pac.** Packaging**approx.** Approximately**SE** square edge**Pcs.** Pieces**Responsible for content**

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The currently valid version can be found at: www.steico.com/tds_steicobase_eur_en